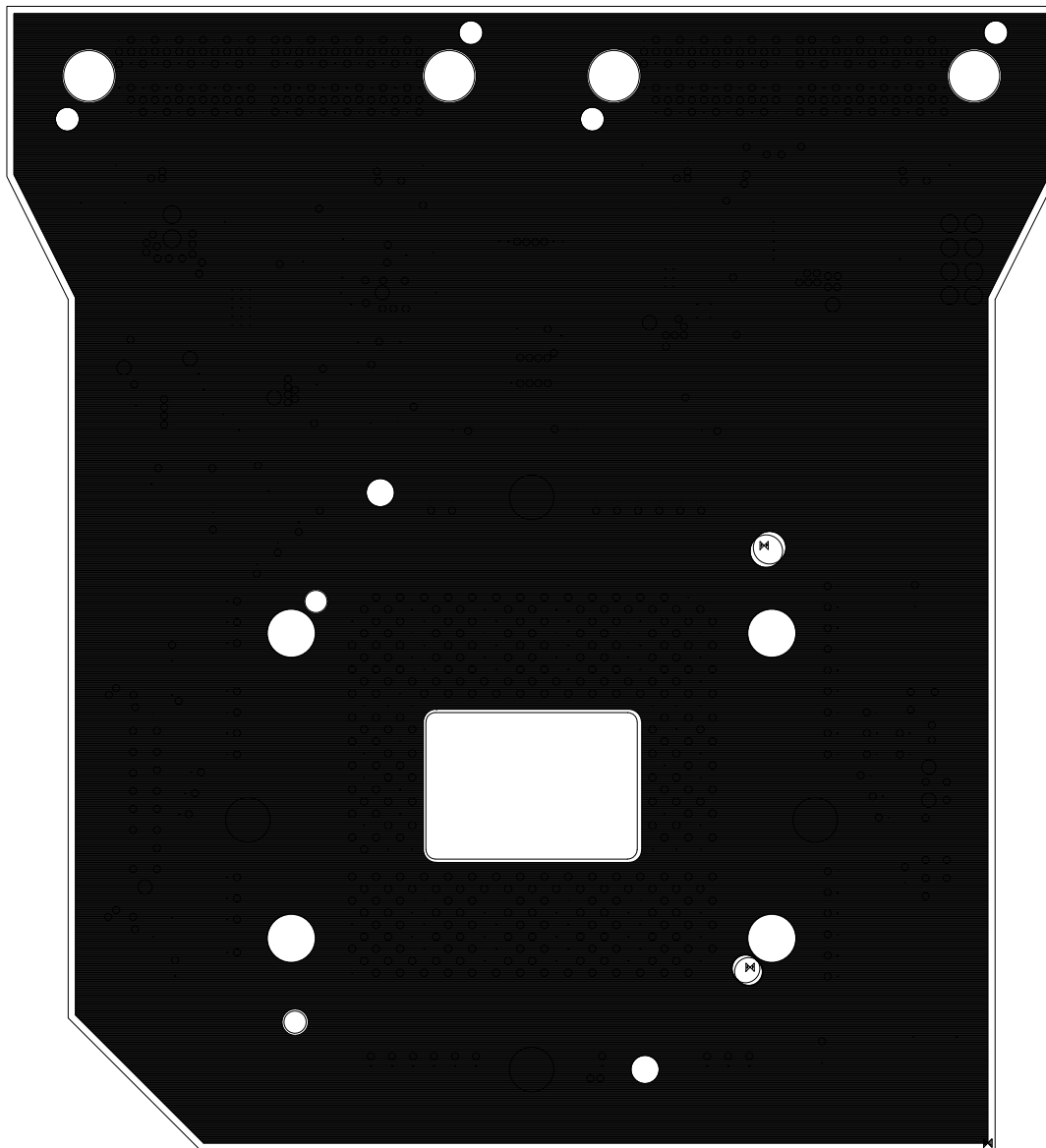
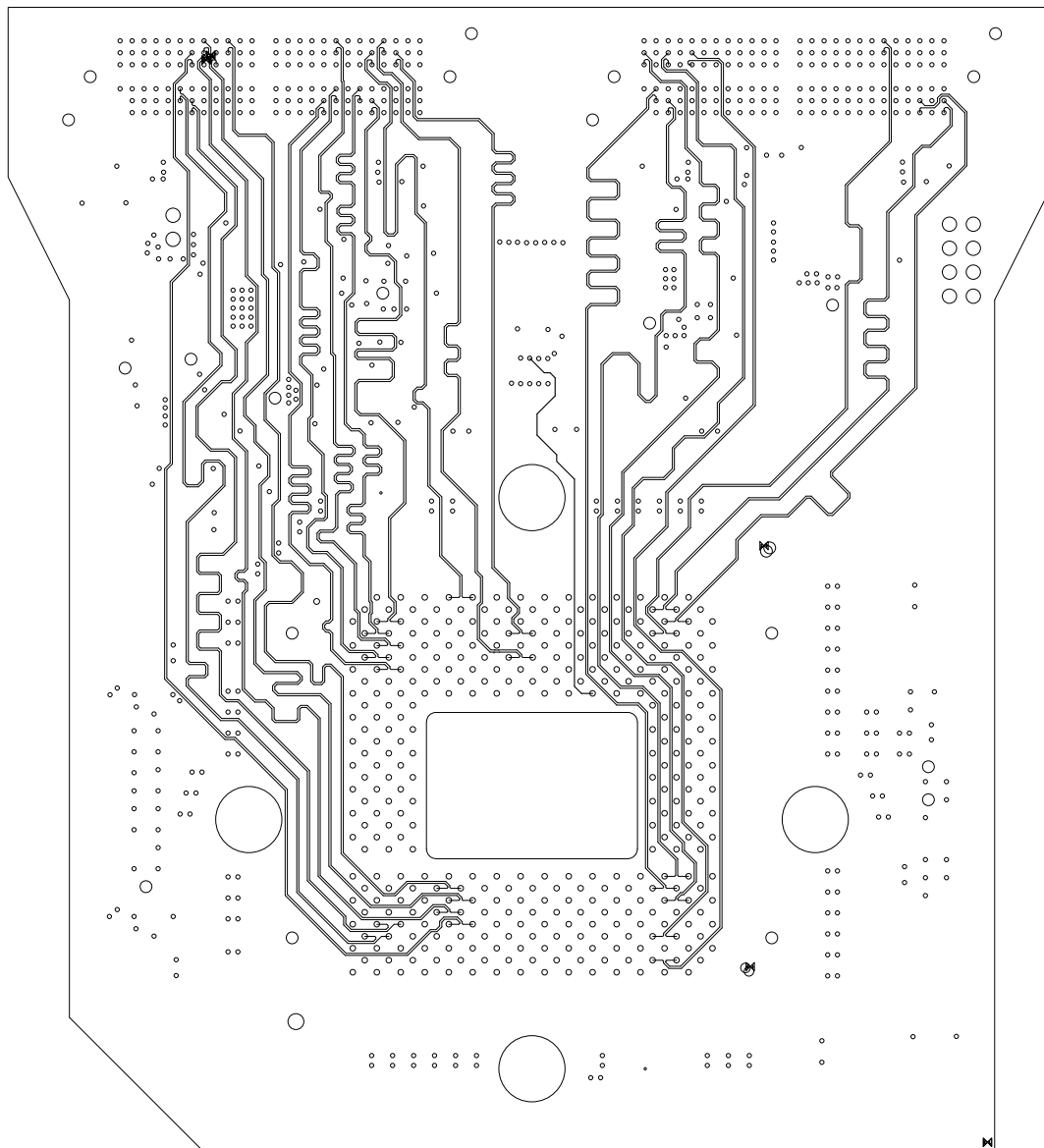


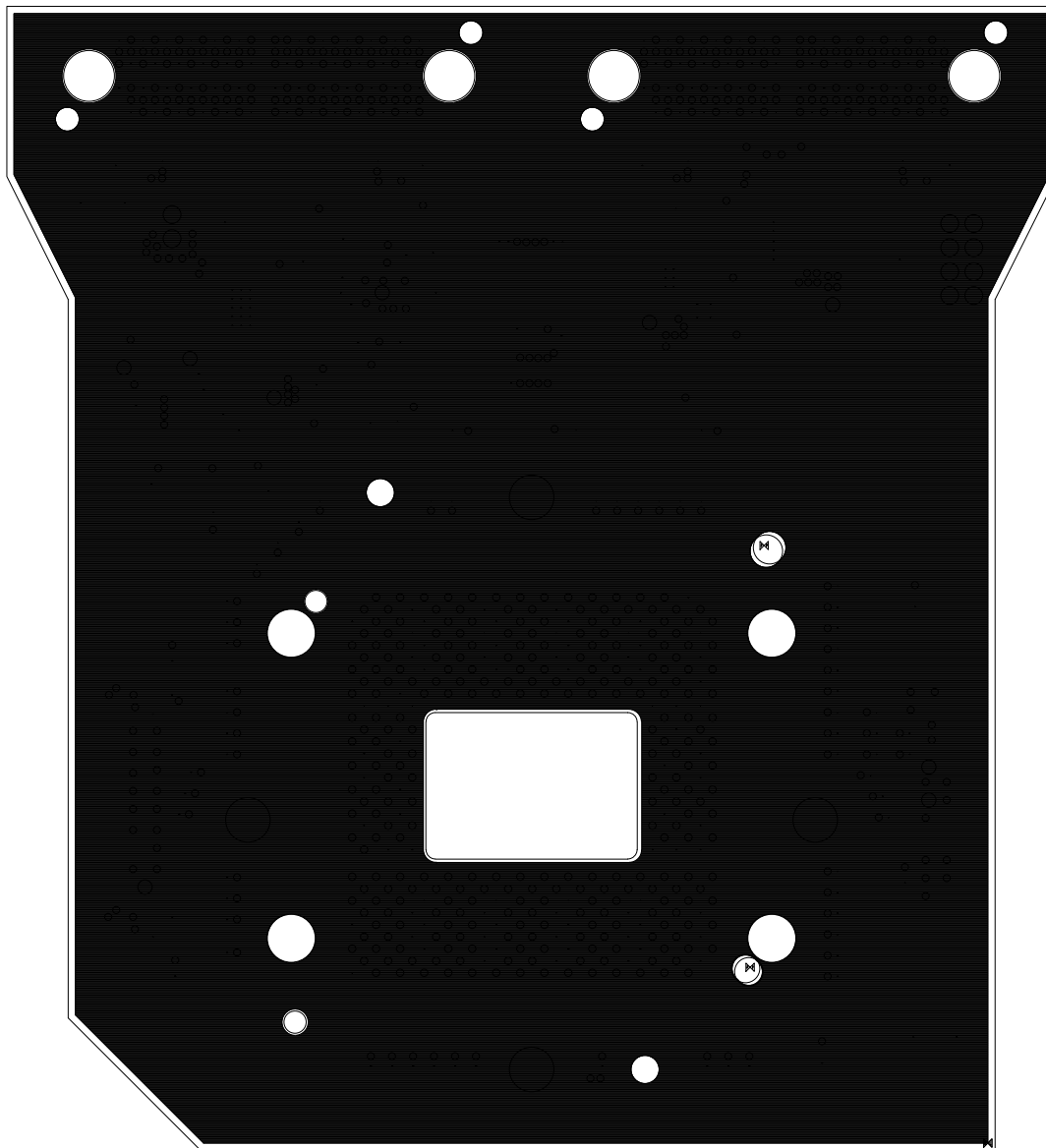
LAYER 1 - PRIMARY SIDE



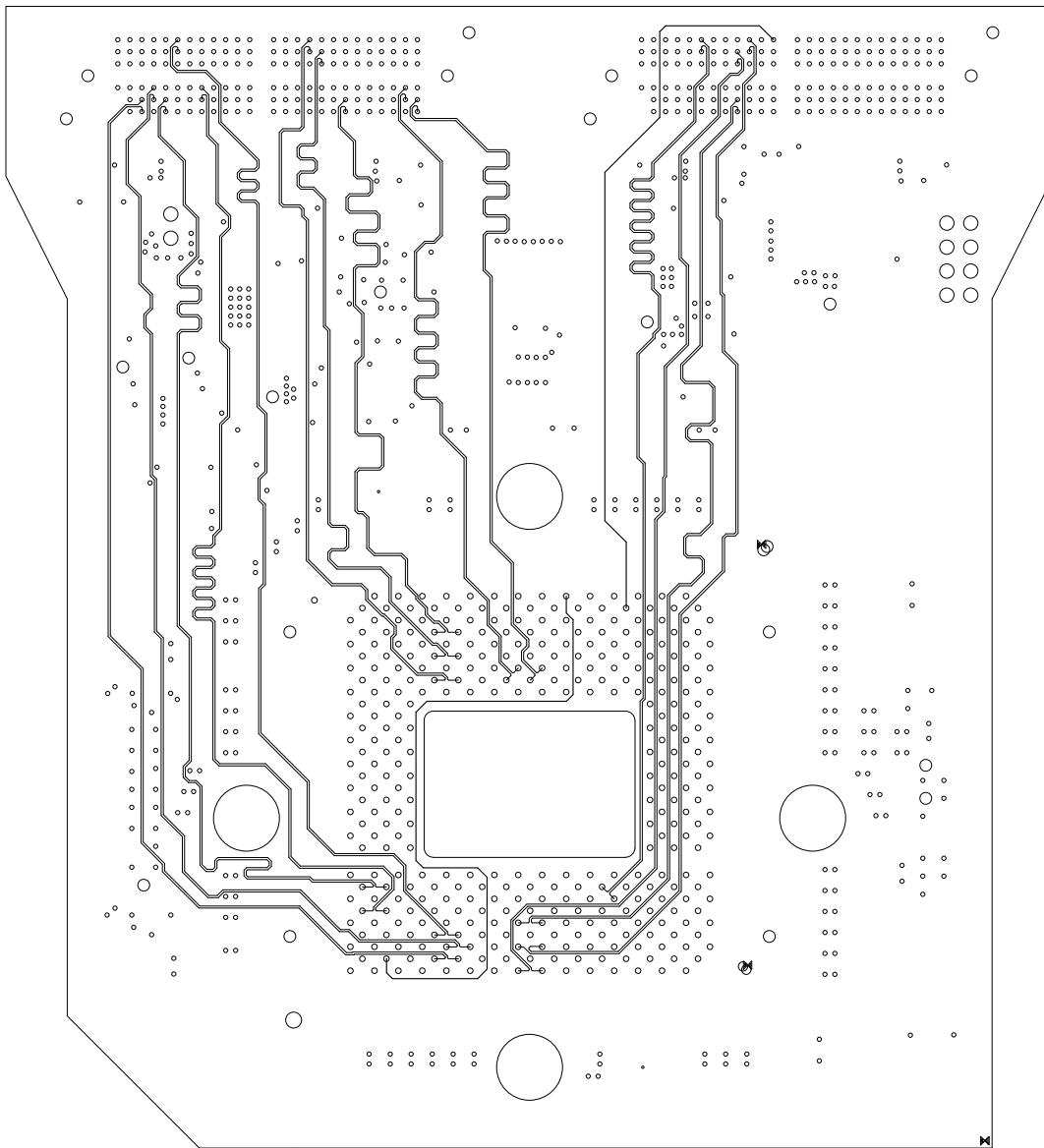
LAYER 2 - GND PLANE



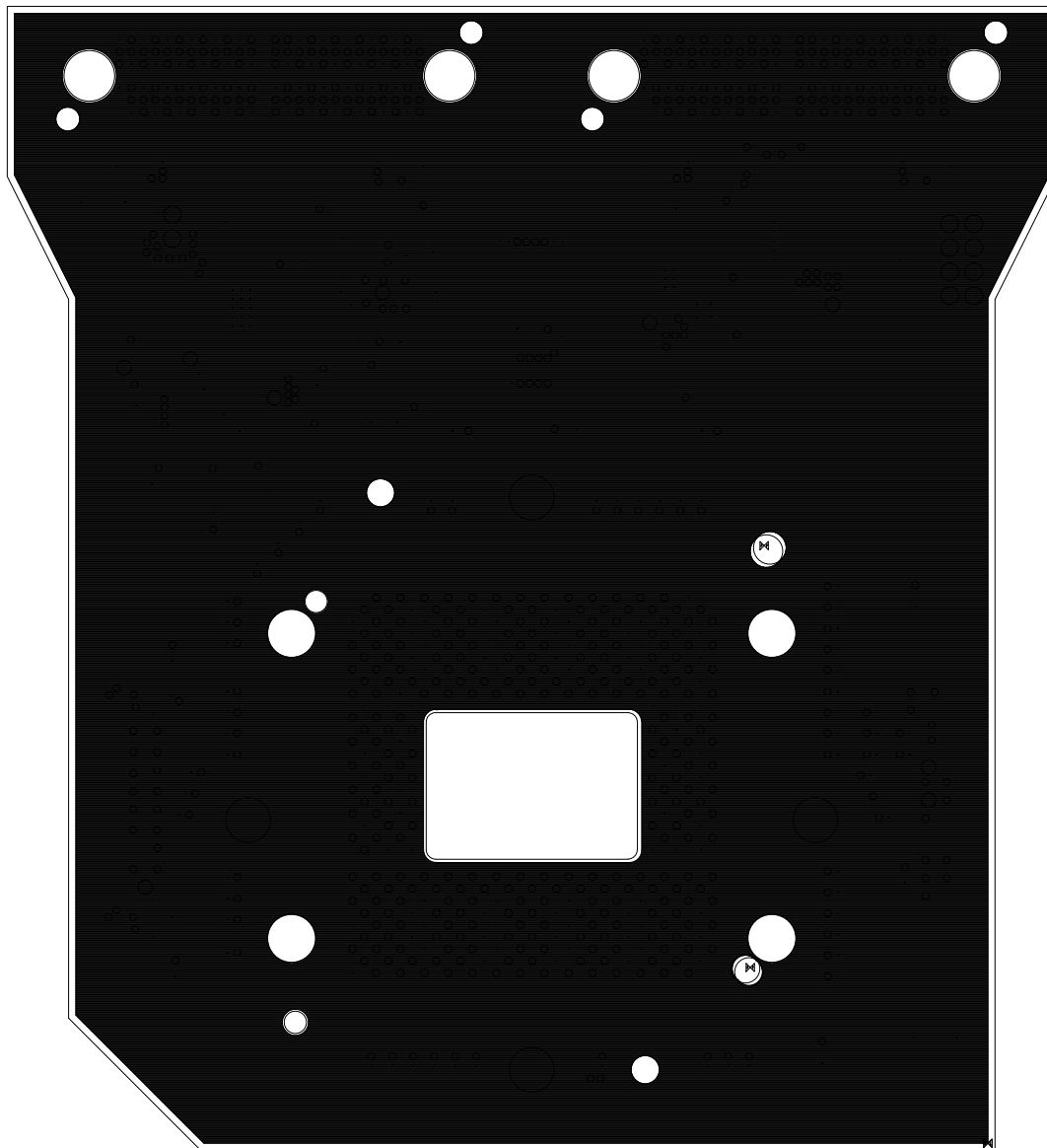
LAYER 3 - SIGNAL



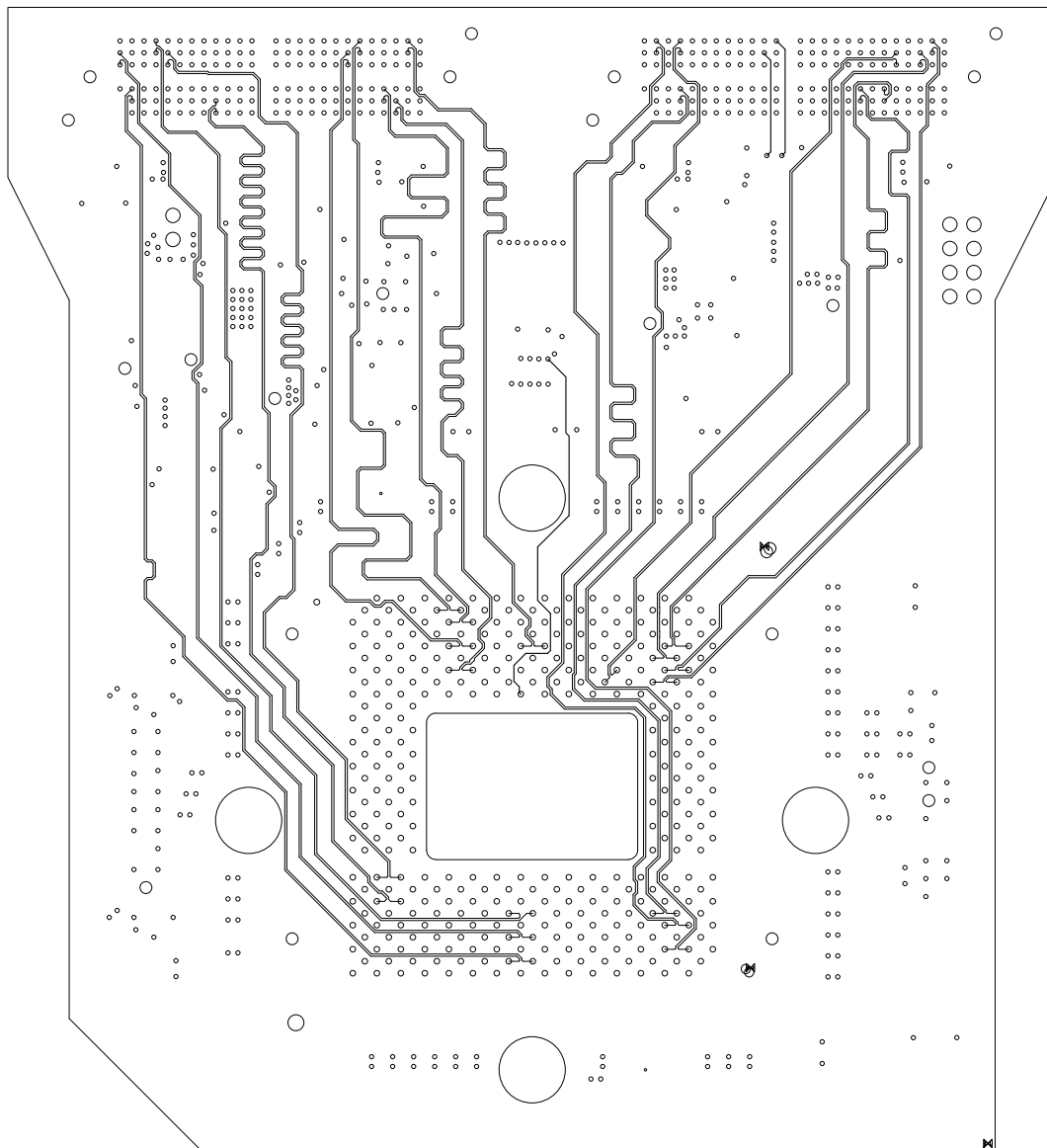
LAYER 4 - GND PLANE



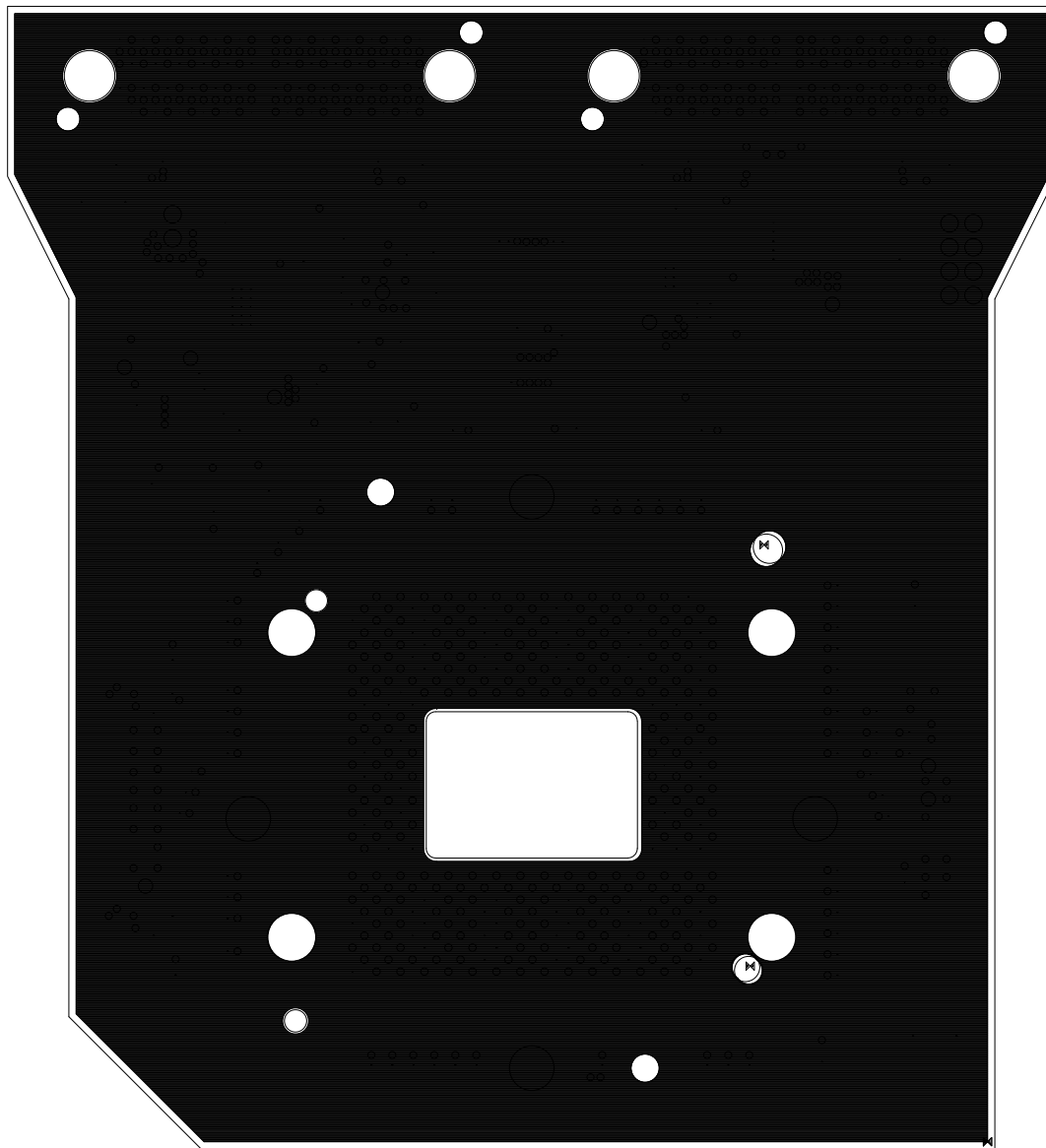
LAYER 5 - SIGNAL



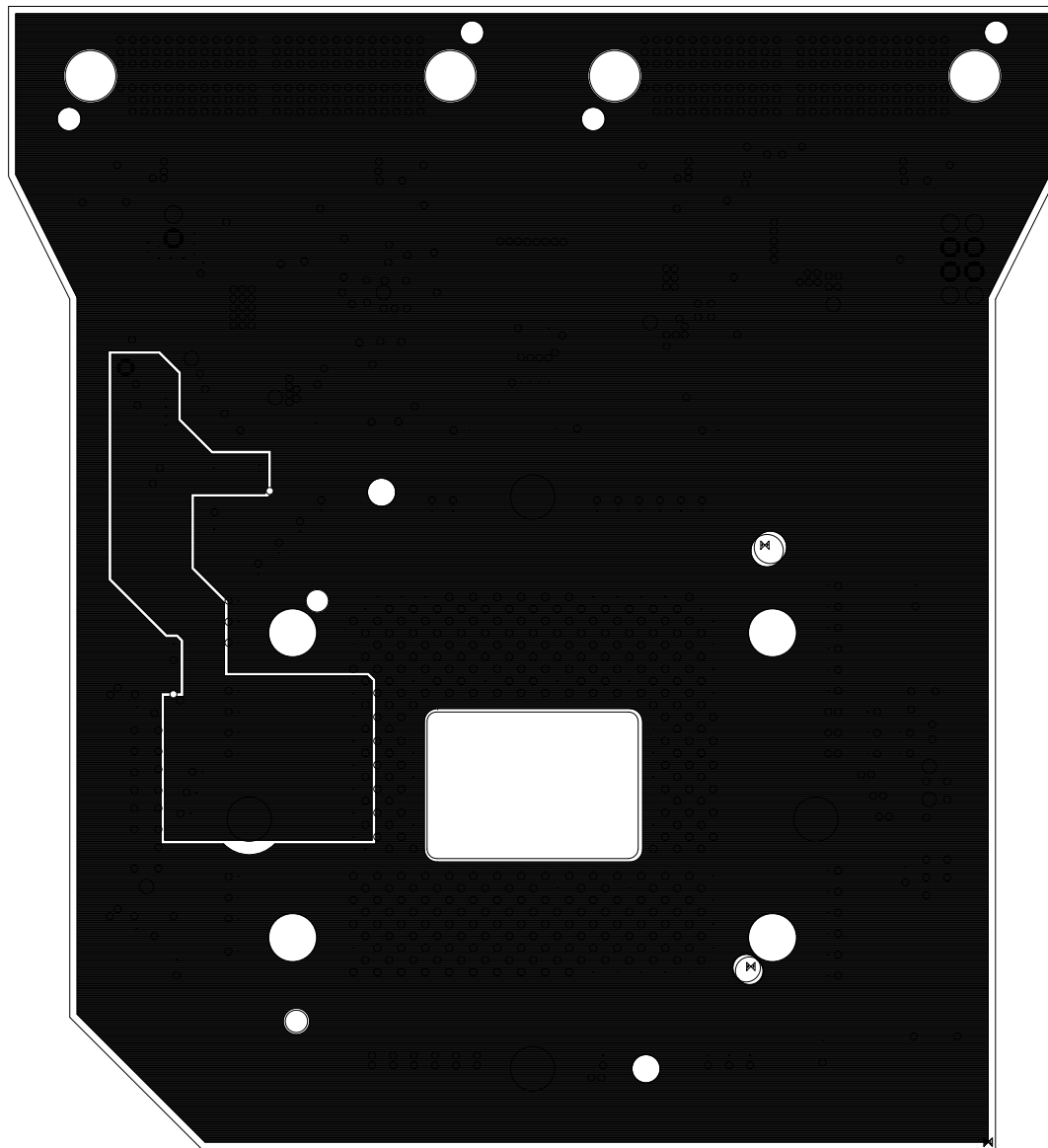
LAYER 6 - GND PLANE



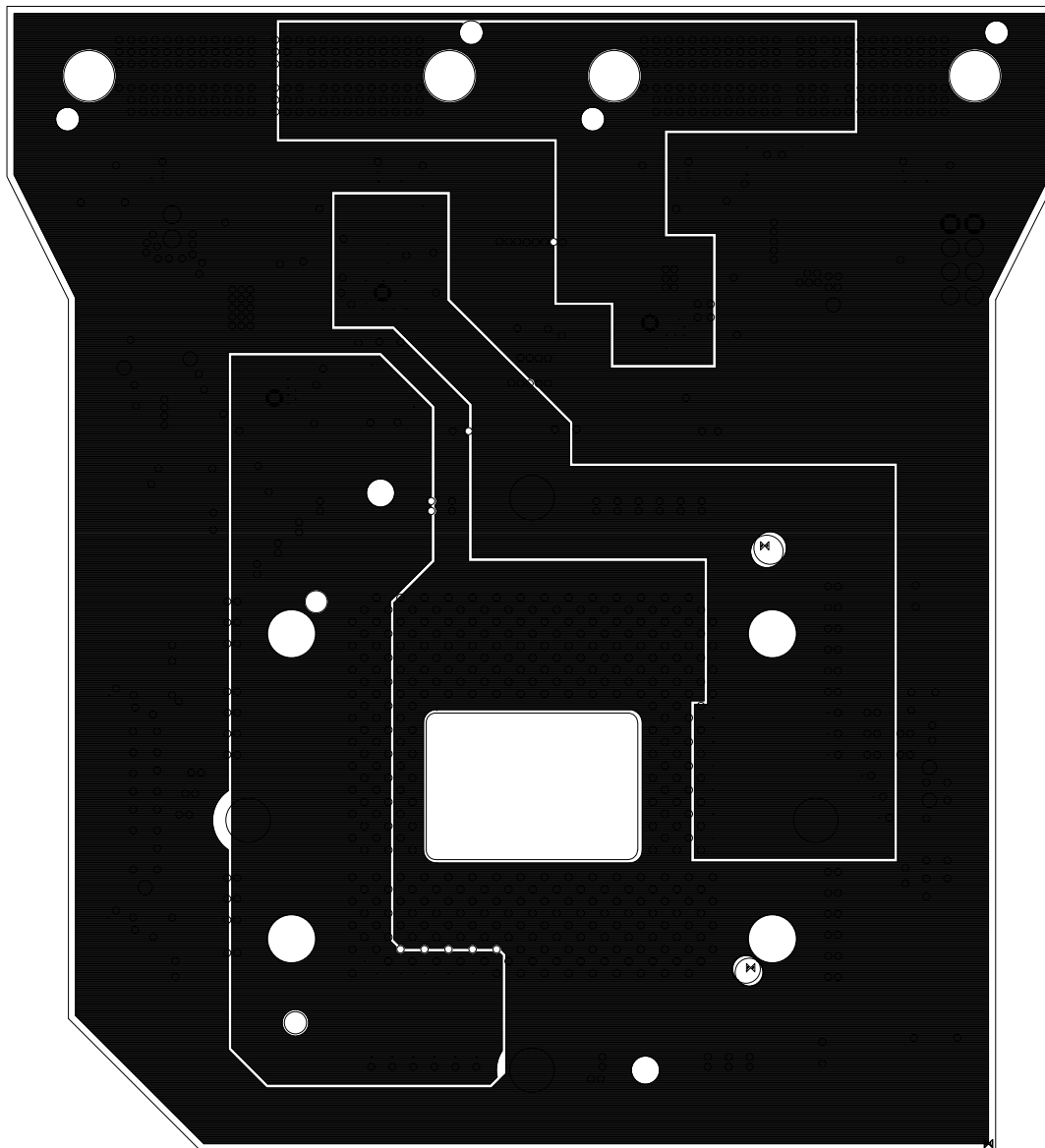
LAYER 7 - SIGNAL



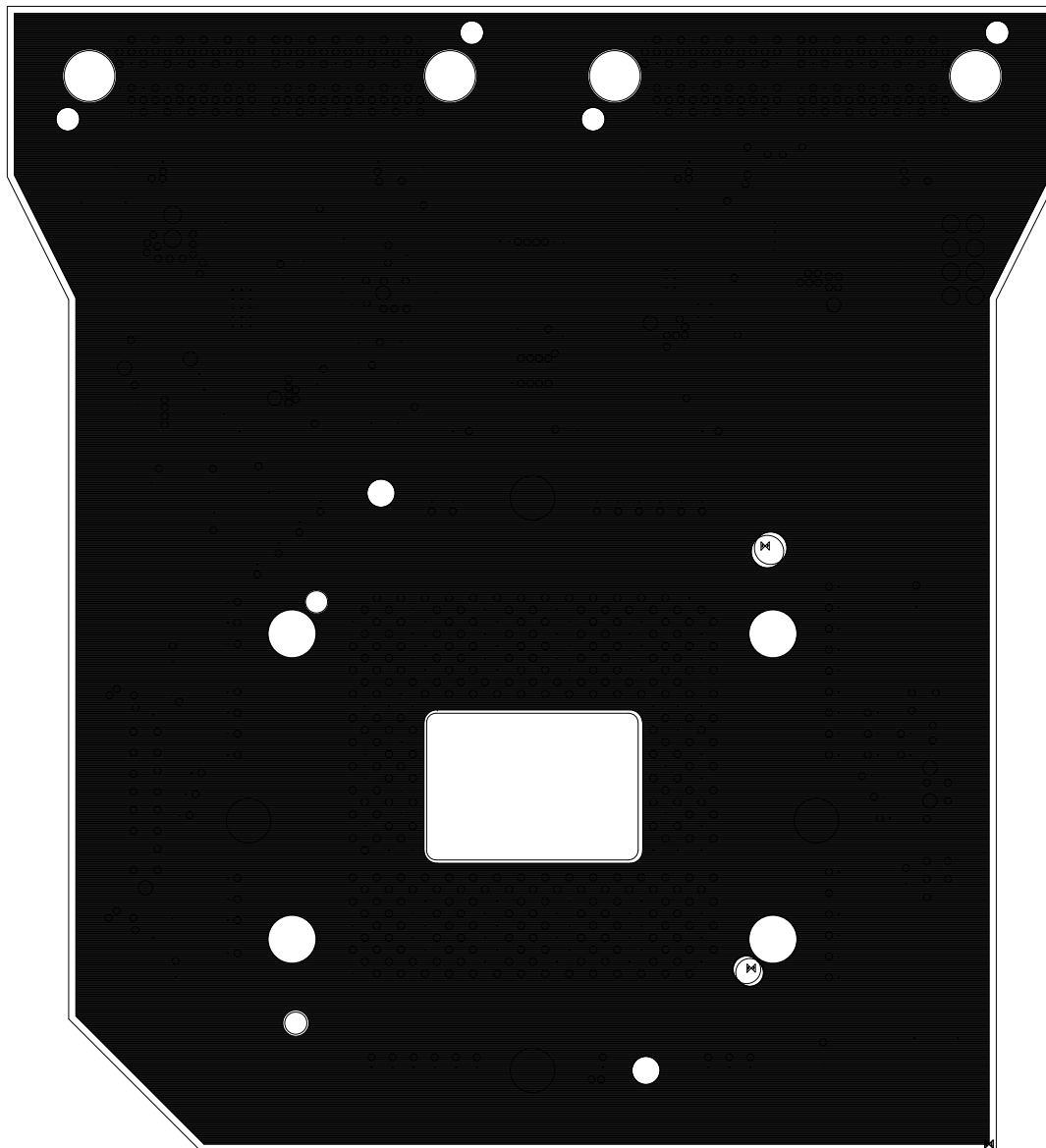
LAYER 8 - GND PLANE



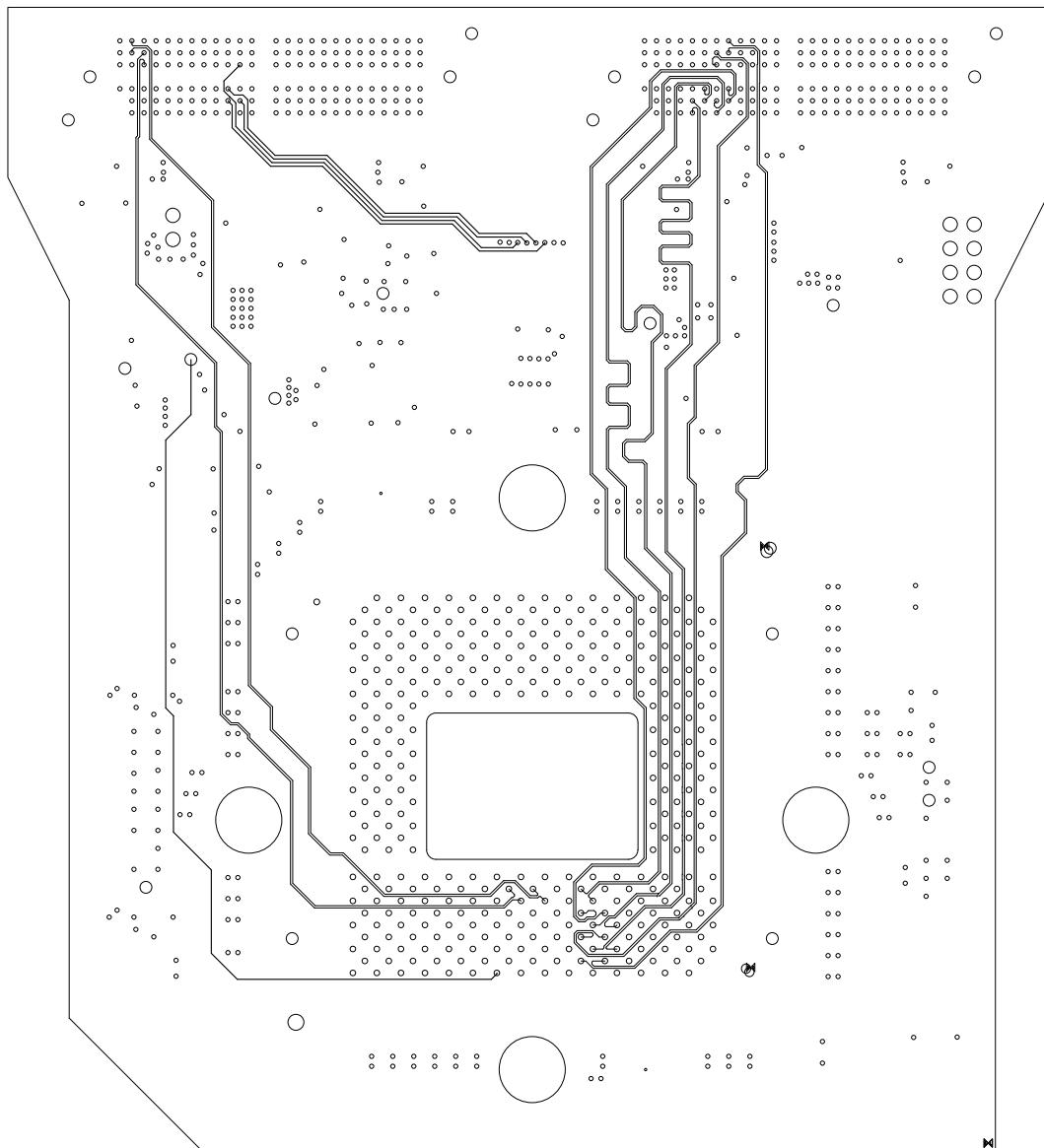
LAYER 9 - PWR PLANE



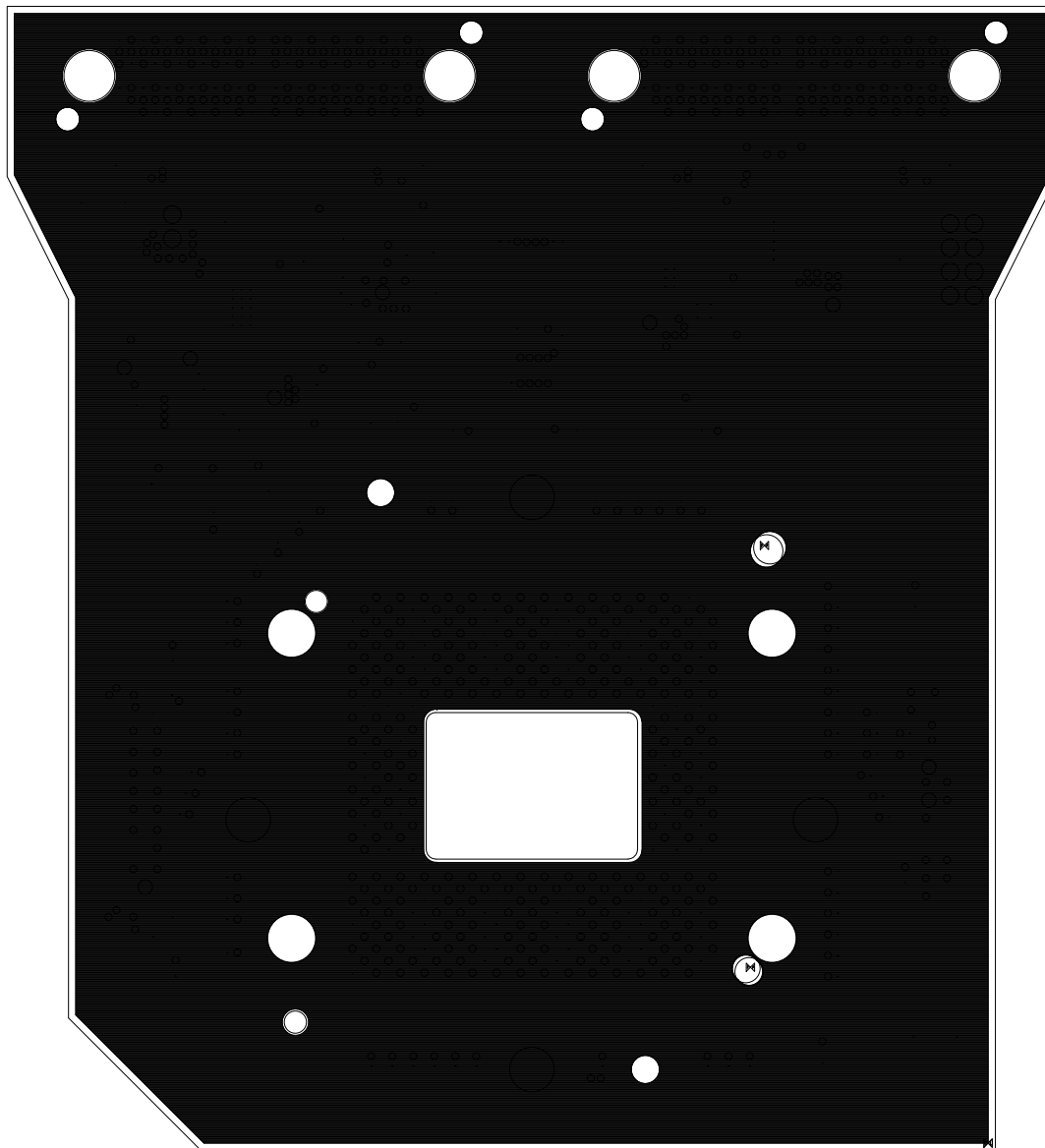
LAYER 10 - PWR PLANE



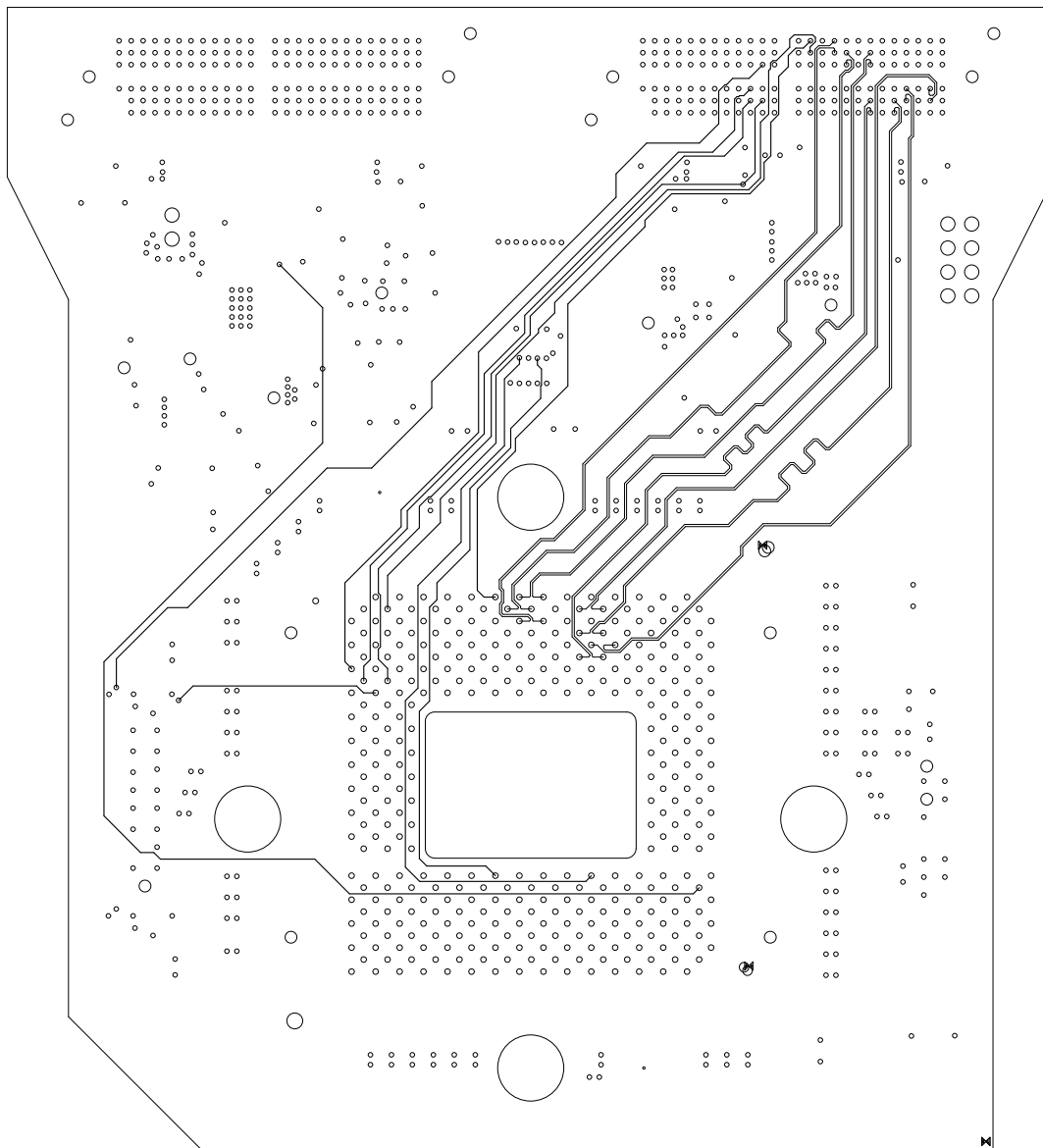
LAYER 11 - GND PLANE



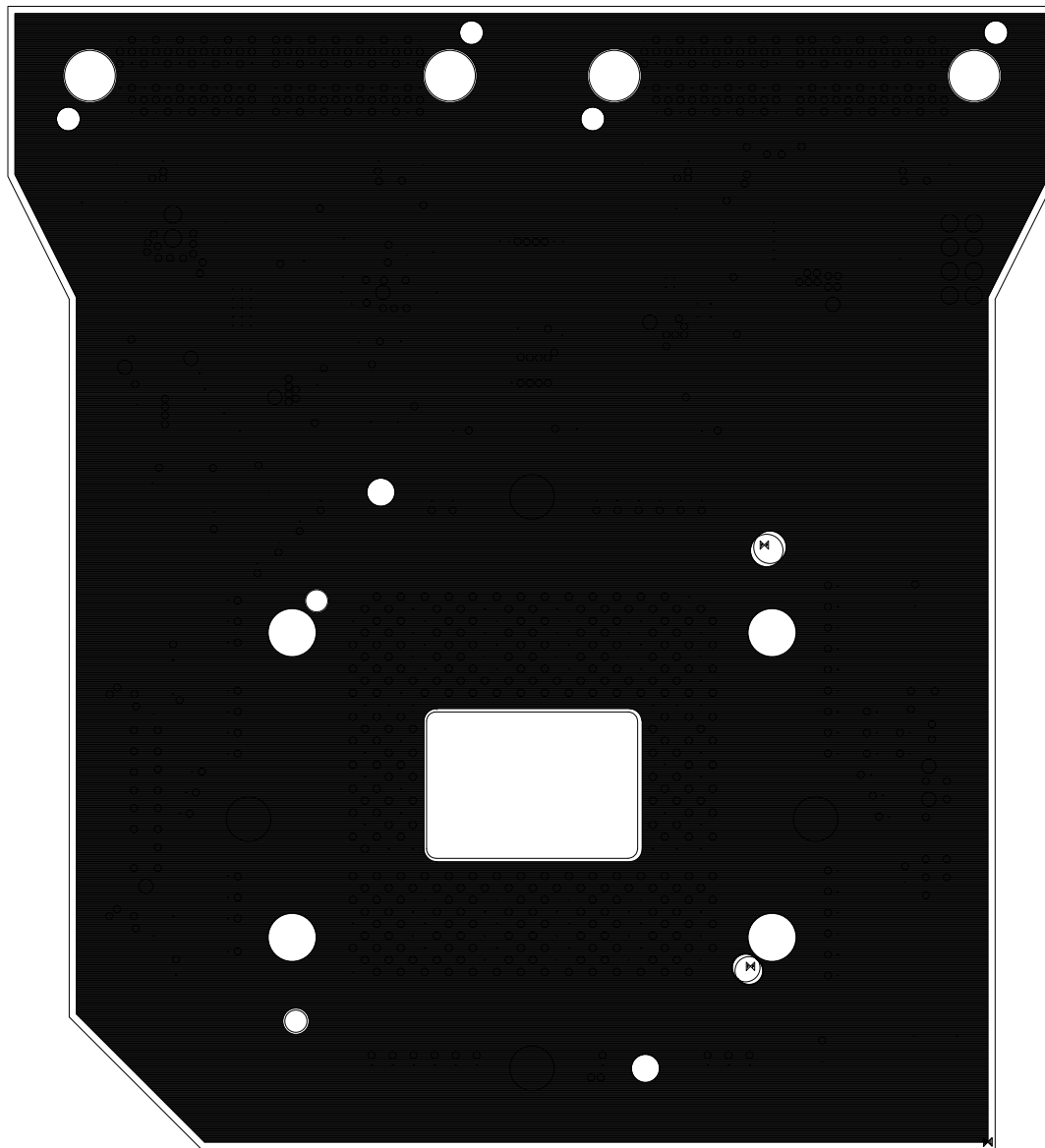
LAYER 12 - SIGNAL



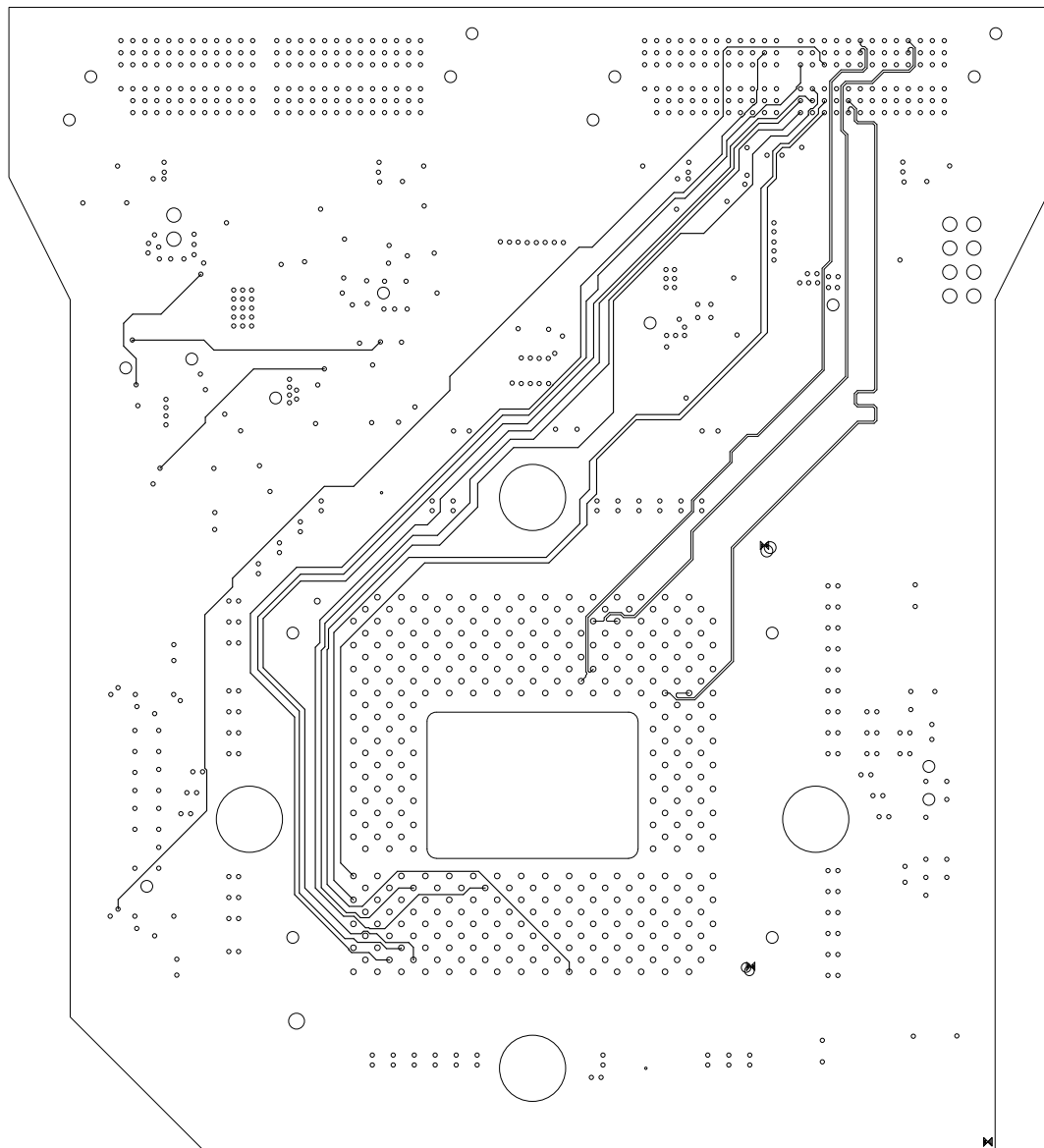
LAYER 13 - GND PLANE



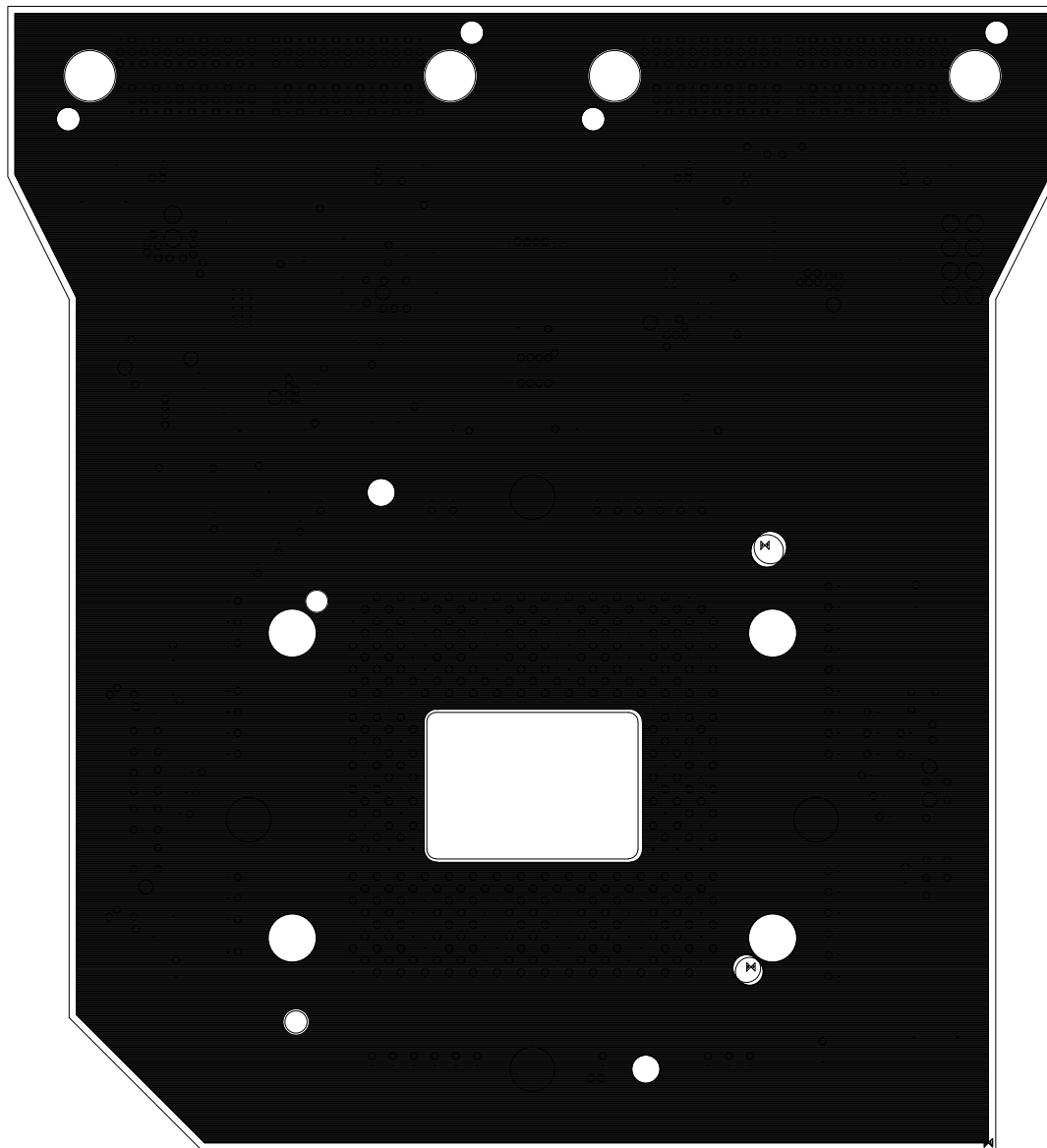
LAYER 14 - SIGNAL



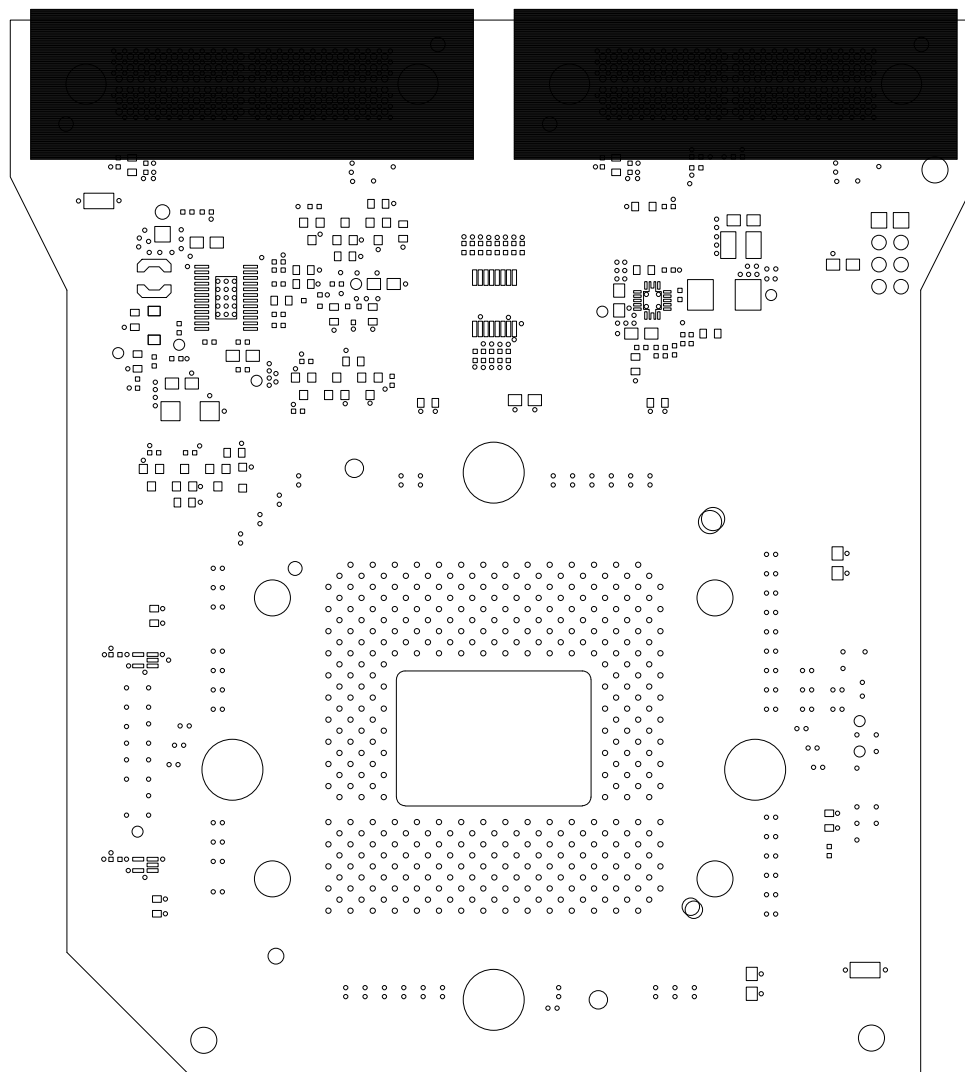
LAYER 15 - GND PLANE



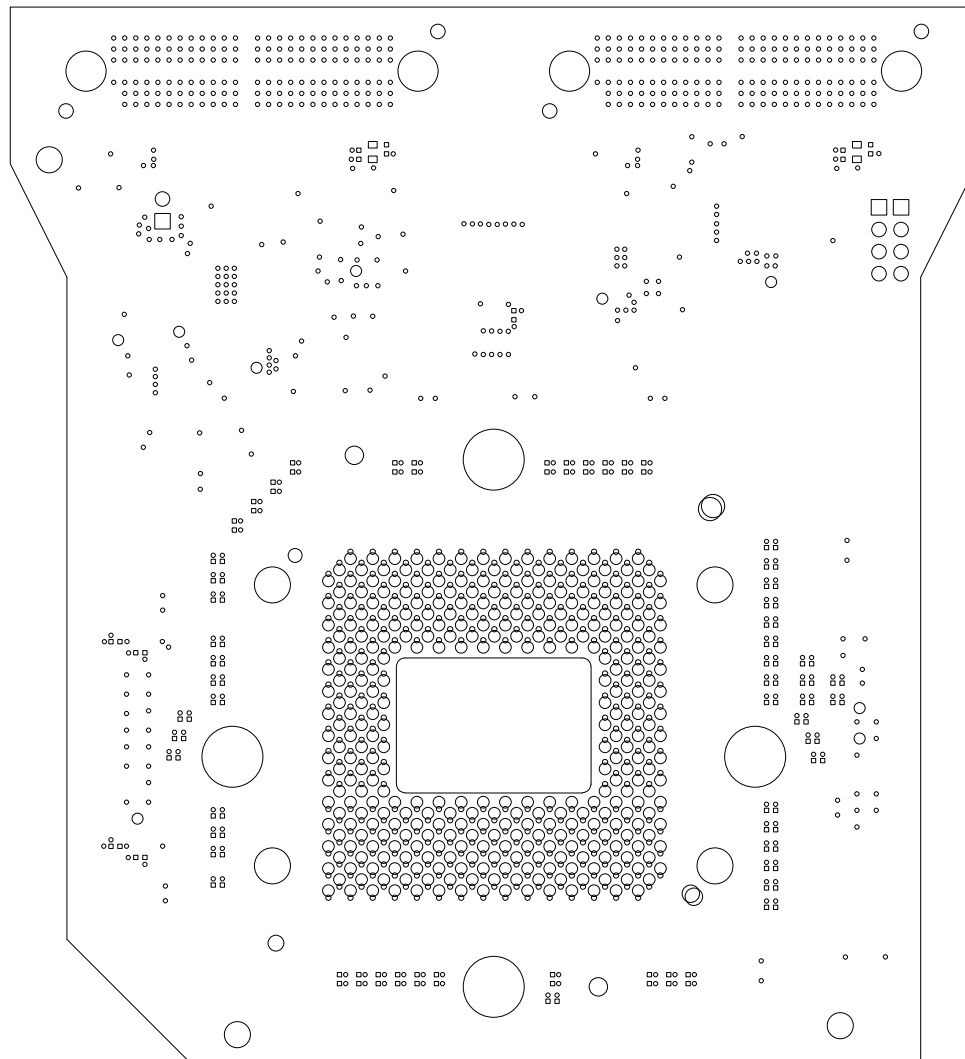
LAYER 16 - SIGNAL



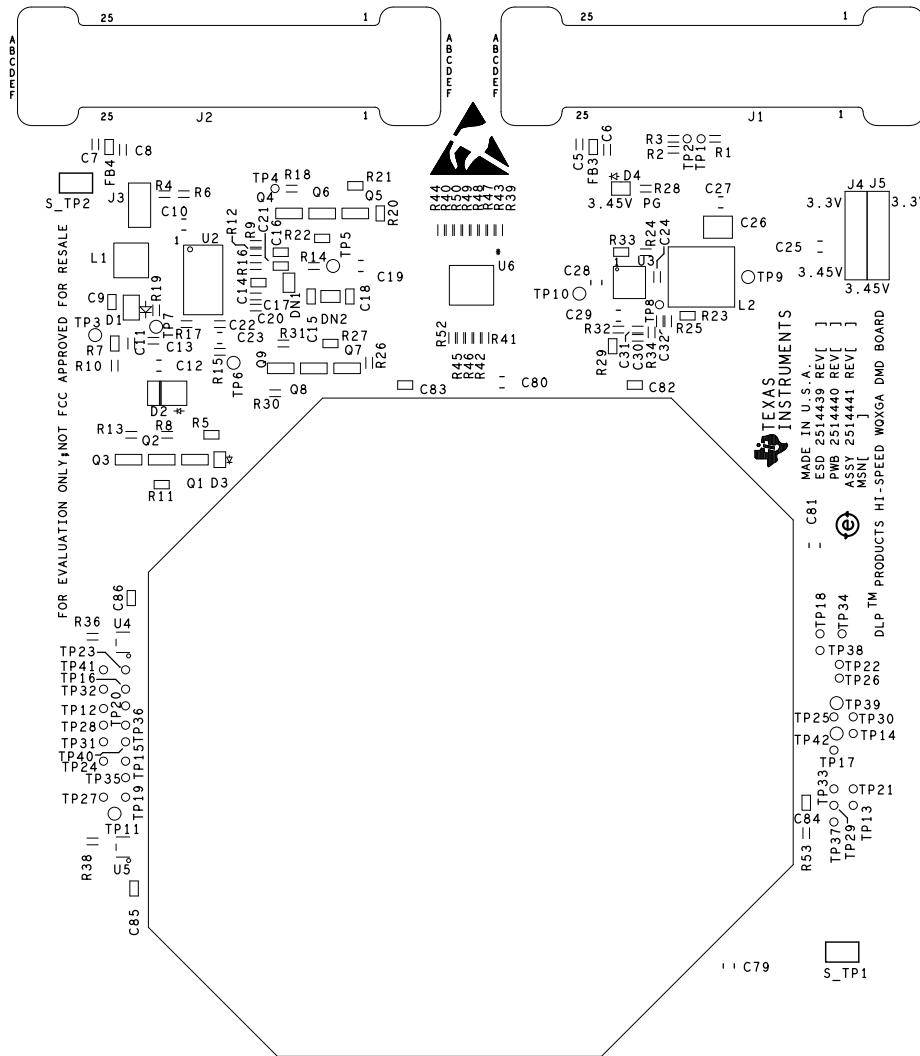
LAYER 17 - GND PLANE



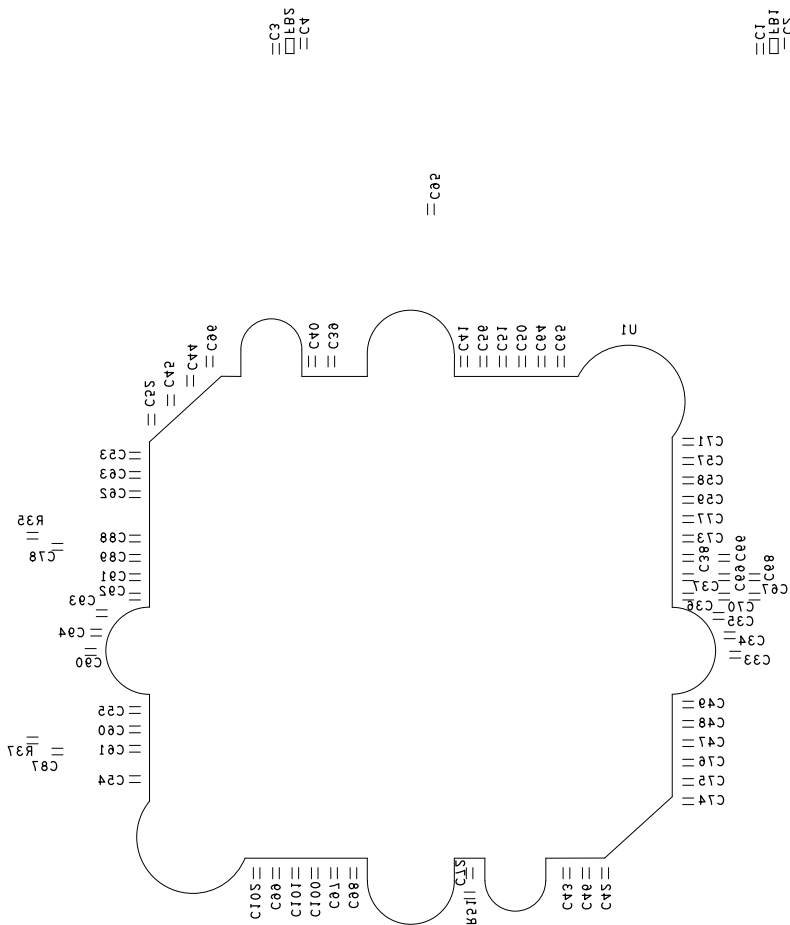
CUSTOMER NAME		TEXAS INSTRUMENTS			
BOARD NAME			DESCRIPTION		
HI SPEED WQXGA DMD BOARD			SOLDERMASK - PRIMARY SIDE		
BOARD NO.	2514440	REV	DATE	PRJ#	SH OF
		B	15-SEP-2015	TIDL P-109680-01	19 25



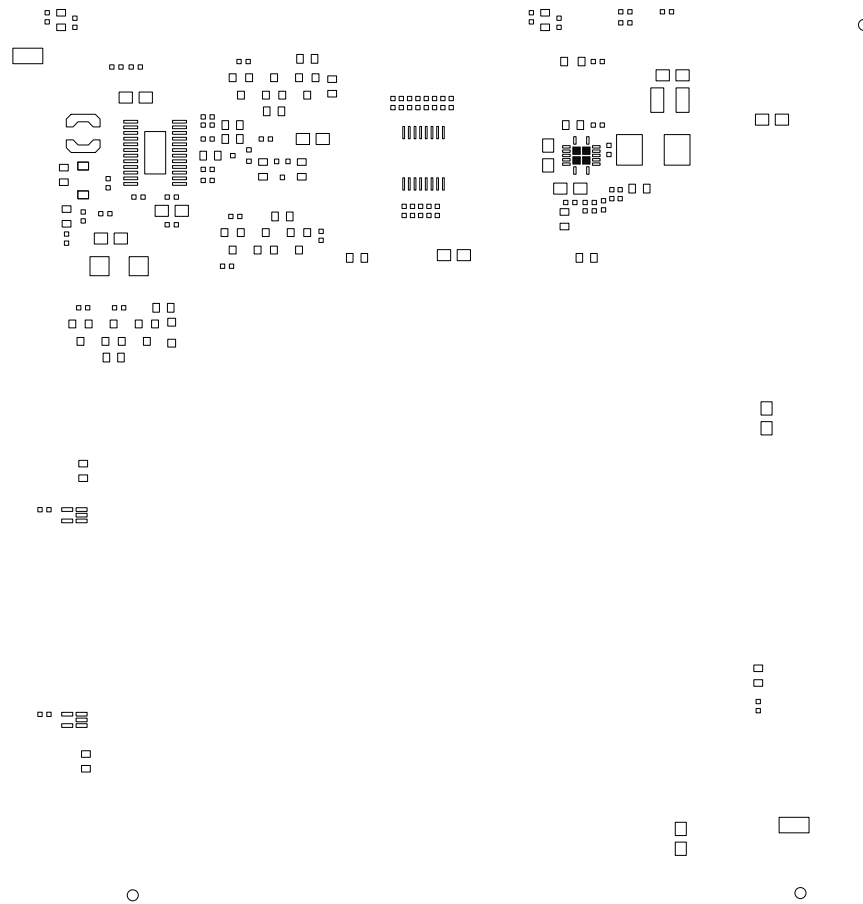
CUSTOMER NAME		TEXAS INSTRUMENTS			
BOARD NAME			DESCRIPTION		
HI SPEED WQXGA DMD BOARD			SOLDERMASK - SECONDARY SIDE		
BOARD NO.	2514440	REV	DATE	PRJ#	SH OF
		B	15-SEP-2015	TIDL P-109680-01	20 25



CUSTOMER NAME		TEXAS INSTRUMENTS			
BOARD NAME			DESCRIPTION		
HI SPEED WQXGA DMD BOARD			SILKSCREEN - PRIMARY SIDE		
BOARD NO.	2514440	REV	DATE	PRJ#	SH OF
		B	17-SEP-2015	TIDL P-110477-01	21 25



CUSTOMER NAME						TEXAS INSTRUMENTS					
BOARD NAME						DESCRIPTION					
HI SPEED WQXGA DMD BOARD						SILKSCREEN - SECONDARY SIDE					
BOARD NO.			REV	DATE	PRJ#	SH	OF				
2514440			B	15-SEP-2015	TIDL P-109680-01	22	25				



CUSTOMER NAME		TEXAS INSTRUMENTS			
BOARD NAME			DESCRIPTION		
HI SPEED WQXGA DMD BOARD			SOLDERPASTE - PRIMARY SIDE		
BOARD NO.	REV	DATE	PRJ#	SH	OF
2514440	B	15-SEP-2015	TIDL P-109680-01	23	25

LAYER STACK-UP - ALL DIMENSIONS IN INCHES				
		50ohm SINGLE ENDED IMPEDANCE CONTROL +/- 10%	90ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%	100ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%
LAYER#	COPPER WEIGHT (OZ)	TRACE WIDTH	TRACE WIDTH / SPACE	TRACE WIDTH / SPACE
LAYER 1 - PRIMARY SIDE - SIGNAL	HALF-PLATING	0.0048		
LAYER 2 - GROUND PLANE	H			
LAYER 3 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 4 - GROUND PLANE	H			
LAYER 5 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 6 - GROUND PLANE	H			
LAYER 7 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 8 - GROUND PLANE	H			
LAYER 9 - SPLIT POWER PLANE	H			
LAYER 10 -SPLIT POWER PLANE	H			
LAYER 11 -GROUND PLANE	H			
LAYER 12 -SIGNAL	H	0.005		0.004/ 0.005
LAYER 13 -GROUND PLANE	H			
LAYER 14- SIGNAL	H	0.005		0.004/ 0.005
LAYER 15 -GROUND PLANE	H			
LAYER 16 -SIGNAL	H	0.005		0.004/ 0.005
LAYER 17 -GROUND PLANE	H			
LAYER 18- SECONDARY SIDE - SIGNAL	HALF-PLATING	0.0048		

1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT TOLERANCES SHALL BE AS FOLLOWS:
 - a. BOARD MATERIAL SHALL BE HITACHI MCL-HE-6790 OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
3. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
4. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
5. OVERALL BOARD THICKNESS TO BE .095 +/- .10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
6. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
7. BOARD MUST BE ELECTRICALLY TESTED USING SQUARED IPC-D-356 NETLIST.
8. NON-PLATED THROUGH SLOTS INDICATED WITH MULTIPLE DRILL HITS SHOULD BE FINISHED AS SMOOTH WALL BY VENDOR.
9. FABRICATOR SHOULD REMOVE ANY UNUSED PADS ON INTERNAL LAYERS.

1. EXCEPT AS NOTED BELOW, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 150 MICROINCHES THK MIN GOLD 5-15 MICROINCHES THK MIN.
1. PLATE ALL THE PAD AREAS OF J1 AND J2 TOP SIDE AND U1 BOTTOM SIDE, WITH A MINIMUM OF 150 AND MAXIMUM 150 MICROINCHES OF ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 100 MICRO-INCHES OF ELECTROLYTIC NICKEL.
2. APPLY LPI SOLDERMASK.
COLOR: BLUE. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV.
3. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS.
FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK.
COLOR: WHITE.

